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GLOBAL IC PACKAGING APPLICATIONS AND OUTSOURCED SEMICONDUCTOR AND TEST (OSAT) MARKETS

2019 EDITION

**A New Comprehensive Report Covering Critical Market
Segments of the Global IC Packaging Industry**

Report Highlights

- **Global Electronics Market Overview**
 - ◆ Economic Overview
 - ◆ Semiconductor Industry Analysis
- **Electronics Summary Forecasts, 2018–2023**
 - ◆ By Total Assembly Value
 - ◆ By Applications Market
- **Semiconductor Application Market Forecasts, 2018-2023**
 - ◆ Unit Shipments and Revenue
 - ◆ By Semiconductor Device
 - ◆ By IC Packaging Type
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- **OSAT IC Packaging Market Forecasts, 2018–2023**
 - ◆ IC Packaging Type by Unit Shipments, Revenues and ASP
 - ◆ Competitive Rankings
 - ◆ 39 Company Profiles

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Synopsis

In the manufacturing of integrated circuits, the role played by the back-end assembly process has changed considerably over the decades. Once important only as a protective housing for the delicate IC devices, IC packages have come to be regarded as integral to the functioning of the ICs, and instrumental in determining the types of electronics we all will purchase in the future.

For more than twenty years, **New Venture Research (NVR)** has provided high quality, in-depth analysis of the IC packaging market. Continuing in that long tradition, NVR announces a new report for 2019: **Global IC Packaging Applications and Outsourced Semiconductor and Test (OSAT) Markets**. This report delves deeply into two critical market segments. The first focus is on the broad domain of applications for which ICs are developed, as well as the end-user electronics products that use ICs. The second focus of the report is on the category of companies known as outsourced semiconductor assembly and test companies, usually referred to by the acronym OSATs, and presents NVR's continuing coverage of this expanding sector of the semiconductor market.

The purpose of the report is to provide an analysis of the major application trends affecting the electronics industry, and detailed forecasts of the major application segments- Consumer, Computer, Communications, Automotive, and Industrial & Other. It also surveys numerous specific electronics product markets, such as smartphones, tablets, PCs, TVs and other consumer products, and automotive components. In addition, the report analyzes the strategies and IC packaging products shipped by OSATs, with forecasts of unit shipments, revenues and ASP. Every table in the report presents historical data for 2018 and forecasts the market for the five-year period, 2019 - 2023.

The 300-page report consists of seven chapters. Chapter 1, "Introduction," and Chapter 2, "Executive Summary." Chapter 3, "Global Electronics Market Trends and Forecasts" presents a critical industry analysis at the global economy today and the broad economic and market trends driving the semiconductor industry. It also details the key electronics products markets for IC devices.

Forecast tables provide not only unit shipments of nearly 30 electronics market segments, but for many the unit shipments of ICs and IC revenues, as well.

Chapter 4, "Overview of the Worldwide IC Packaging Market" describes in detail the many IC packaging market segments and provides forecasts of the worldwide market in terms of packaging types, I/O count and IC devices. This sets the stage for Chapter 5, "IC Applications Analysis," which examines semiconductor device applications and IC packaging applications in terms of unit shipments and revenues.

In Chapter 6, "OSAT Market and Strategy Analysis," the report examines the history of outsourcing in the semiconductor market and the emergence of the OSAT contractors, as a major factor in the IC packaging market. The chapter presents the market shares for the leading OSATs and analyzes their product marketing strategies. Tables present forecasts of the OSAT market in terms of unit shipments, revenues and package pricing. Finally, Chapter 7, "OSAT Company Profiles" presents concise profiles of nearly 40 OSAT companies, providing a cross-section of both large and small competitors, as well as companies specializing in both conventional IC packaging and leading-edge advanced IC packaging products.

Global IC Packaging Applications and Outsourced Semiconductor and Test (OSAT) Markets - 2019 Edition is an effective and economical tool for any company interested in competing in the semiconductor industry as an aid in assessing the present and future of this dynamic industry. The report sells for \$3995 and is delivered by email as a single-user PDF file. Extra single-user licenses sell for \$500 each and a corporate license is available for an additional \$1500. With the purchase of the report, an Excel spreadsheet containing every table and graphic may be obtained for an additional \$1000 and a printed copy for \$250.

About The Author

Jerry Watkins is an independent senior analyst with more than 20 years of direct experience in the field of market research and consulting. He has worked for leading research companies such as Frost & Sullivan, Lucid Information Services, and NSI Research, both in management and as a writer. Mr. Watkins has authored many syndicated reports, previously in the telecommunications and office automation sectors and more recently in the semiconductor industry, writing on subjects that include IC packaging and merchant embedded computing. He holds two university degrees, including a B.A. in History and an M.A. in International Studies, but he feels that market research best fulfills his lifelong passion for inquiry into difficult subject matter and making it comprehensible to a wide audience. Mr. Watkins has lived and worked in Silicon Valley for most of his career.

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